

Material Declaration Report

Package Type:	SOIC 14L (150mil)
Pericom Package Code:	W14(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	129.060
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	9/15/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	77.626	UTL and SPEL	Silica Fused	60676-86-0	88.000	68.3107
			Epoxy Resin	Proprietary	5.000	3.8813
			Phenolic Resin	Proprietary	4.500	3.4932
			Epoxy, Cresol Novolac	29690-82-2	2.000	1.5525
			Carbon Black	1333-86-4	0.500	0.3881
LEADFRAME	46.156		Copper	7440-50-8	97.021	44.7808
			Iron	7439-89-6	2.350	1.0847
			Silver	7440-22-4	0.453	0.2092
			Zinc	7440-66-6	0.111	0.0511
			Phosphorus	7723-14-0	0.065	0.0300
SILICON DIE	1.216		Silicon (Si)	7440-21-3	99.192	1.2060
			Non-hazardous Metal	Proprietary	0.808	0.0098
DIE ATTACH EPOXY	0.267	UTL	Silver	7440-22-4	80.000	0.2135
			Functionalized Urethane	72869-86-4	8.000	0.0214
			Diester Resin	94-80-4	7.000	0.0187
			Epoxy Resin	Proprietary	5.000	0.0133
			Silver	7440-22-4	80.000	0.2135
		SPEL	Epoxy Resin	9003-36-5	10.000	0.0267
			Diluent	26447-14-3	6.000	0.0160
			Hardener	620-92-8	3.250	0.0087
			Dicyandamide	461-58-5	0.750	0.0020
GOLD WIRE	0.201		Gold(Au)	7440-57-5	99.990	0.2011
			Impurities	-	0.010	0.0000
SOLDER PLATING	3.595		Tin (Sn)	7440-31-5	99.990	3.5941
			Impurity	-	0.010	0.0004

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.</p> <p>X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>							